



## Material Content Data Sheet



<b>Sales Product Name</b>		IPG20N10S4-36A		<b>Issued</b>		22. January 2018		
<b>MA#</b>		MA001606870						
<b>Package</b>		PG-TDSON-8-10		<b>Weight*</b>		98.79 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.114	2.14	2.14	21395	21395
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		141	
	non noble metal	iron	7439-89-6	0.046	0.05		470	
	non noble metal	copper	7440-50-8	46.380	46.95	47.01	469478	470089
	non noble metal	aluminium	7429-90-5	0.743	0.75	0.75	7518	7518
wire	non noble metal	aluminium	7429-90-5	0.743	0.75	0.75	7518	7518
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		909	
	plastics	epoxy resin	-	6.379	6.46		64567	
	inorganic material	silicondioxide	60676-86-0	38.452	38.92	45.47	389223	454699
leadfinish	non noble metal	tin	7440-31-5	1.396	1.41	1.41	14135	14135
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		15	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6105	6120
solder	non noble metal	tin	7440-31-5	0.051	0.05		521	
	noble metal	silver	7440-22-4	0.064	0.07		651	
	non noble metal	lead	7439-92-1	2.457	2.49	2.61	24872	26044
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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